

REV.	REVISIONS DESCRIPTION	DATE	APPROVED
-	INITIAL RELEASE	8/12/2010	E. TANGEN

NOTES:

- CONSTRUCTION: 1 oz. Cu TOP LAYER,  
ROGERS 4003 8 MIL THICK DIELECTRIC, 1 oz. Cu BOTTOM LAYER.  
FINISHED BOARD THICKNESS APPROX 14 MILS  
SOLDERMASK TOPSIDE ONLY, COLOR - BLUE
- FINISH PLATING:
  - NICKEL TYPE: ASTM B733-97, CLASS 1, 3-8  $\mu$ m THICK, 7-9% PHOSPHORUS.
  - GOLD TYPE: IMMERSION GOLD .03-.2  $\mu$ m THICK.
- HOLE PLATING: COPPER MIN. .0008.
- MECHANICAL/HOLE LOCATION TOLERANCES: MECHANICAL  $\pm$ .005, HOLE LOCATION TOLERANCE  $\pm$ .003 TO TOP VIEW, TOP LAYER.
- PATTERN ACCURACY  $\pm$ .001 FROM 1:1 ARTWORK.
- MUST COMPLY WITH EU RoHS DIRECTIVE 2002/95/EC.
- SEE SHEET 2
- SEE SHEET 4
- SEE SHEET 5

<small>DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE SPECIFIED. TOLERANCES ARE:</small> DEC.XX= $\pm$ .020    FRAC. $\pm$ .XXX= $\pm$ .005    ANG. $\pm$ .XXXX= $\pm$ .0020 REMOVE BURRS, BREAK SHARP EDGES MATERIAL: SEE NOTES FINISH: SEE NOTES		<small>SIGNATURES</small> ORIG. E. TANGEN MFG. ENG. QA.	<small>DATE</small> 8/12/2010	<b>TriQuint</b> <small>SEMICONDUCTOR</small> 500 W Renner Road Richardson, Texas 32860-9501 Tel: (972) 994-3727
SALES PCB FOR, TGA4532/3-SM EVALUATION BOARD		<small>SIZE DWG.NO.</small> A 9xxxxx		<small>REV</small> --
<small>SCALE: NONE</small>		<small>PCB, TGA4532/3-SM</small>		<small>SHEET 1 OF 5</small>

SEE NOTE 7

SEE NOTE 8

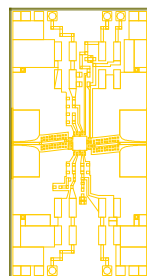
7. LETTERING SHOWN TO BE SILKSCREENED ON TOP OF FINISHED BOARD.

8. SILKSCREEN THE FOLLOWING ON TOP LAYER, IN AN AREA THAT DOES NOT INTERFERE WITH ANY FEATURES:

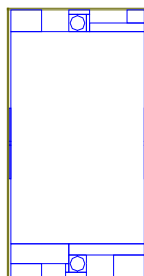
- TRIQUINT DOCUMENT NUMBER AND REVISION.
- MANUFACTURER NAME OR LOGO.
- DATE CODE.

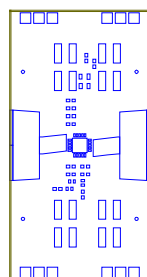
<small>SIZE DWG.NO.</small> A 9xxxxx		<small>REV</small> --
<small>SCALE: NONE</small>		<small>PCB, TGA4532/3-SM</small>
<small>SHEET 2 OF 5</small>		



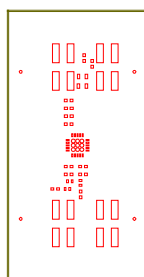
TOP VIEW  
TOP METAL



TOP VIEW  
BOTTOM METAL

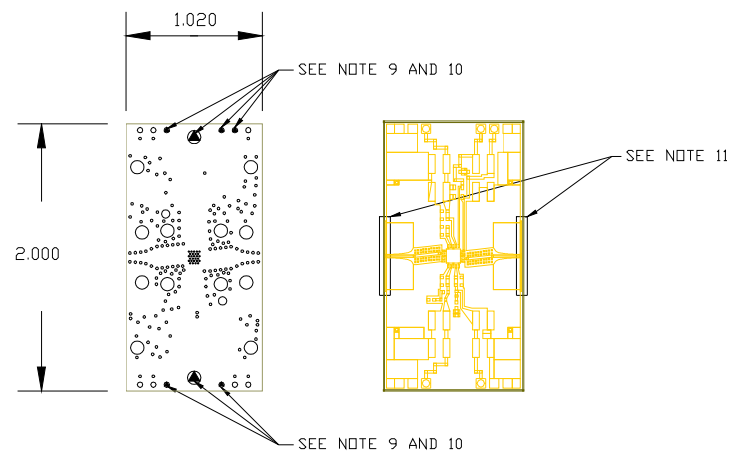
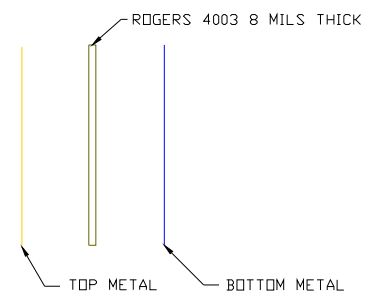


TOP VIEW  
TOP SOLDERMASK



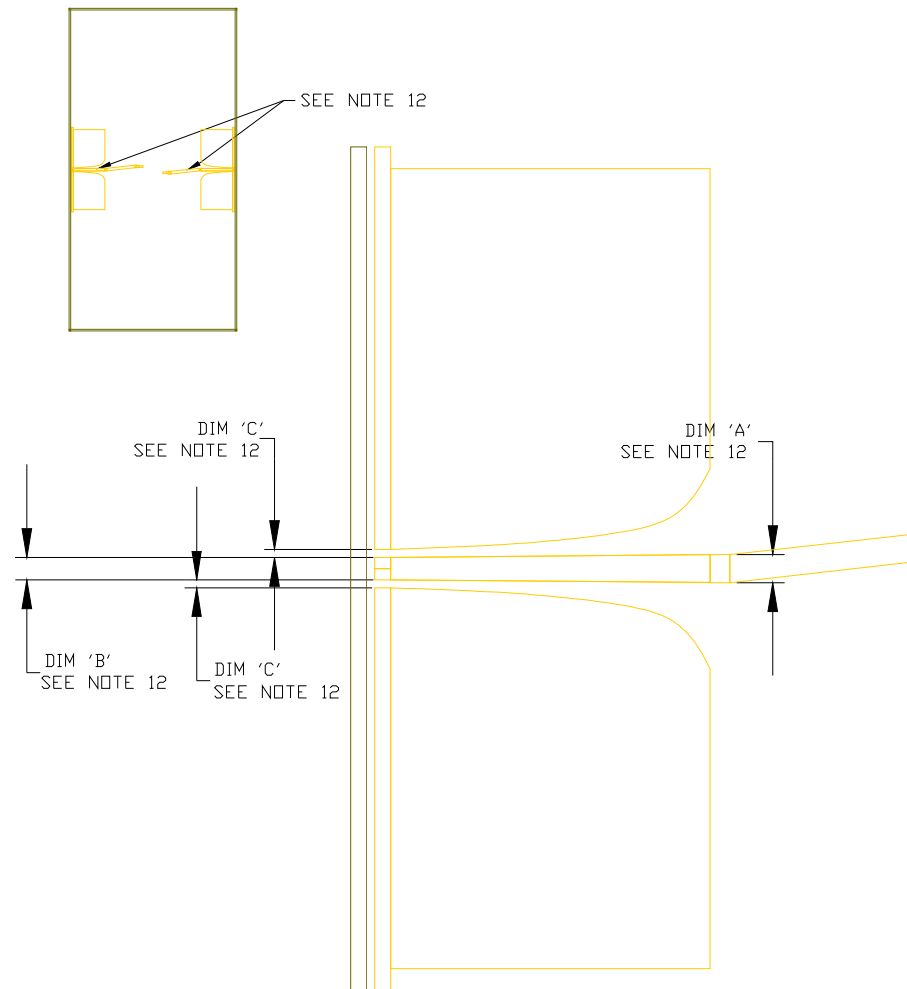
TOP VIEW  
SOLDERPASTE

SIZE	DWG.NO.	REV
A	9xxxxx	--
SCALE: NONE	PCB, TGA4532/3-SM	SHEET 3 OF 5



- NOTES:
- HOLES MARKED '▲' ARE NON PLATED THRU (<7 PLACES)
  - ALL UNMARKED HOLES ARE PLATED THRU.
  - BOARD TO BE PANELIZED AS A TABBED ARRAY.  
THERE SHALL BE NO SOLDERMASK OR BREAKAWAY TABS  
IN THE AREAS HIGHLIGHTED.

SIZE	DWG.NO.	REV
A	9xxxxx	--
SCALE: NONE	PCB, TGA4532/3-SM	SHEET 4 OF 5



NOTES:

12. CRITICAL IMPEDANCE TRACES.

FINAL DIMENSION AND TOLERANCE OF THESE TRACES LISTED BELOW:

DIM 'A' .0175"  $\pm$ .001"  
 DIM 'B' .014"  $\pm$ .001"  
 DIM 'C' .005"  $\pm$ .0005"

SIZE A	DWG.NO. 9xxxxx	REV A
SCALE: NONE	PCB, TGA4532/3-SM	SHEET 5 OF 5